

First Circular and Call for Papers

SIMC-XIII-2004

13th Semi-conducting and insulating Materials Conference

September 20-25, 2004

Beijing, China.



The SIMC-XIII is organized by the Institute of Semiconductors, Chinese Academy of Sciences. The conference is sponsored by the IEEE Electron Devices Society, the Chinese Academy of Sciences, the National Natural Science Foundation of China and some companies related to the field covered by the conference scope.

Introduction

The 13th Semi-conducting and Insulating Materials Conference (SIMC-XIII 2004) will be held during September 20- 25, 2004 in Beijing, China. Beijing is a city of contrasts. On one hand, it's a fast becoming a modern city of first-class hotels, business

centers, shopping malls and wide avenues. But then there are the Hutongs, those ageless communities of narrow streets that have changed little over the past 7 hundred years.

The SIMC is a series of bi-annual conferences initiated in 1980 in Nottingham (UK). The purpose of the meeting is to provide an opportunity for scientists and engineers from both the academic sphere and industry to meet together for an efficient scientific exchange on the topics related to the fundamental materials problems of compound semiconductors, which are widely used for electronic and optoelectronic devices. SIMC has been a forum for many informal and friendly discussions on many materials issues of importance for device applications.

Topics of the Conference

A tentative list of the topics that will be addressed during the conference is:

- Semi-insulating III-V compounds,
- Non-Stoichiometric III-V compounds
- Narrow band gap nitrides such as GaAsN and GaAsPN etc,
- Wide gap materials such as GaN, AlGaN, AlGaInN, SiC and ZnO etc,
- Nanomaterials and technologies
- Novel materials and
- All kinds of devices emerging from these materials.

The conference program will include invited, oral and poster presentations.

Abstract submission

Authors wishing to contribute a paper should submit an abstract of about 300-500 words in English to the conference chairman by 10th May 2004. The abstract should contain the authors' names and affiliations. Please underline the name of the presenting author. And affiliations should include full mailing addresses, if possible, phone and fax numbers as well as e-mail addresses of the corresponding author.

The best way to send your abstract is by email: zgwang@red.semi.ac.cn

Important deadlines

2 nd circular:	January 2004
Abstract deadline:	May 10,2004
Notification of acceptance:	July 1, 2004

Conference site

The detailed conference site in Beijing will be found from the 2nd circular or through the Web site later this year.

Travel and transportation

To be added in 2nd circular of the conference.

Conference Chairman

Wang Zhanguo

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Conference Secretary

To be chosen soon

International Advisory Committee

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More to be added

Organizing Committee

Shengchun Qu, Institute of Semiconductors, CAS, (China)
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Weixin Duan, Institute of Semiconductors, CAS, (China)
More to be added